

L Number	Hits	Search Text	DB	Time stamp
-	0	"temporary flip-chip connection"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/09 10:42
-	8068	flip-chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/07 18:01
-	2046	"temporary connection"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/07 18:39
-	62	flip-chip and "temporary connection"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/07 18:13
-	162640	solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/09 10:10
-	406	refreeze	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/07 18:13
-	1	flip-chip and solder and refreeze	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/07 18:13
-	1	flip-chip and refreeze	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/07 18:13
-	0	"temporary connection" and refreeze	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/07 18:25
-	2	("4875617").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/07 18:37
-	21	4875617.URPN.	USPAT	2002/11/07 18:25
-	17	5038996.URPN.	USPAT	2002/11/07 18:35
-	10	"flip chip testing"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/07 18:37
-	1063	"temporary bonding" or temporary adj bond	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/07 18:40
-	20	flip-chip and ("temporary bonding" or temporary adj bond)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/07 18:40

-	52	solder and indium and tin and lead and conductive adj bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:11
-	0	(eca or "electrically conductive adhesive") and ("diemat" or staystik) and melting adj temperature	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:44
-	11	(eca or "electrically conductive adhesive") and ("diemat" or staystik)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:45
-	71	("diemat" or staystik)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:53
-	0	"multilayerd solder bump"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:53
-	0	"multilayerd solder"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 11:21
-	582	(438/108).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 11:21
-	2	("5290732" "6107180").PN.	USPAT	2002/11/09 11:42